R/LRDIMM Validation Compliance Sheet Form

Must accompany all modules submitted for Web Validation Please ensure that all cells are completely filled out E-mail a copy of this form to the test lab prior to your shipment and attach paper hardcopy with shipment package.	
Supplier Information	
Module Vendor	
Key Contact Name	
Key Contact Phone	
Key Contact e-mail	
Module Information	
Sample Quantity	
Module Technology (DDR3, DDR3L, etc)	
Module Type (RDIMM, UDIMM, SoDIMM, etc)	
Module Part Number	
Module Capacity / Size	
SPD revision	
Speed / Frequency	
Module Core Timings (CL-tRCD-tRP)	
Number of DRAM Dies	
Number of DRAM packages	
Number of Ranks	
ECC?	
Part Availability (Mass Production, ES, etc	
SDRAM Information	
SDRAM Part Number	
SDRAM Supplier	
SDRAM Density (Die)	
SDRAM Width (x8, x4)	
SDRAM Package Type (uBGA, TSOP, etc)	
SRAM Process Technology (nm)	
SDRAM Die Revision (A-Die, Rev B, etc)	
SDRAM Date Code	
SDRAM Speed	
SDRAM Core Timings CL– tRCD - tRP	
SDRAM Validated?	
PCB Information	
Raw Card Type	
Gerber Revision	
Is Gerber JEDEC compliant?	

Register/Memory Buffer Information		
Register/Memory Buffer Vendor		
Register/Memory Buffer Part Number		
Register/Memory Buffer Revision		
Register/Memory Buffer Date Code		
Register/Memory Buffer Validated (Yes/No)?		
Thermal Sensor Information		
Thermal Sensor Top Marking		
Thermal Sensor Type		
Thermal Sensory Accuracy Rating		
Thermal Sensor Vendor		
Thermal Sensor Part number		
Thermal Sensor Device ID/Revision # Register code (2 bytes value, ex. 0x0001)		
Heat Spreader Information		
Heat Spreader Vendor		
Heat Spreader Revision		
Heat Spreader Material		
Heat Spreader Part Number (Front and Back)		
Heat Spreader Thickness (Front and Back)		
Heat Spreader Register/MB Punch Depth Height		
TIM (Thermal Interface Material) Information		
	On DRAM	On Register/MB
Manufacturer		
Part number		
Type (grease, phase change, pad, etc.)		
Thickness (after assembly)		
Temp Cure Required? If yes, what temp & how long?		
Sample Submission		
Reason for submission (Evaluation, Resubmission, etc)		
Submission for which platform		